

Silicon Carbide (SiC) MOSFET - 40 mohm,

NVHL040N120SC1

ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	1200	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, referenced to 25°C	-	450	-	mV/°C
Zero Gate Voltage Drain Current	o Gate Voltage Drain Current I_{DSS} $V_{GS} = 0 \text{ V}, V_{DS} = 1200 \text{ V},$		_	_	100	μΑ
		V _{GS} = 0 V, V _{DS} = 1200 V, T _J = 175°C	_	_	250	
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +25/–15 V, V _{DS} = 0 V	-	_	±1	μΑ
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$, $I_D = 10 \text{ mA}$	1.8	2.97	4.3	V
Recommended Gate Voltage	V_{GOP}		-5	_	+20	V
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 20 \text{ V}, I_D = 35 \text{ A}, T_J = 25^{\circ}\text{C}$	_	39	56	mΩ
		V _{GS} = 20 V, I _D = 35 A, T _J = 175°C	_	•	•	

NVHL040N120SC1

TYPICAL CHARACTERISTICS

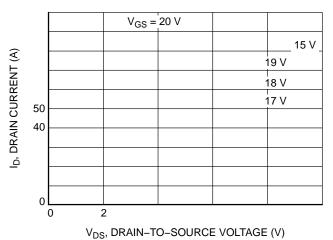


Figure 1. On-Region Characteristics

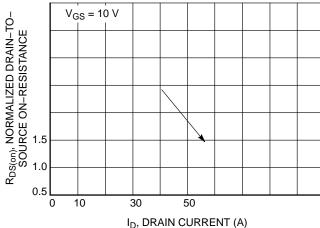


Figure 2. Normalized On–Resistance vs. Drain Current and Gate Voltage

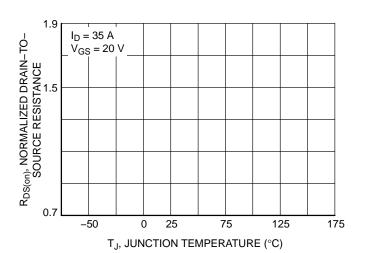
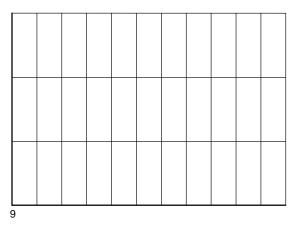


Figure 3. On–Resistance Variation with Temperature



 $\label{eq:VGS} V_{GS}, \, \text{GATE-TO-SOURCE VOLTAGE (V)}$ Figure 4. On–Resistance vs. Gate-to–Source

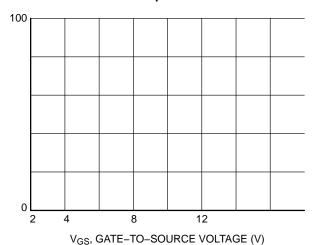
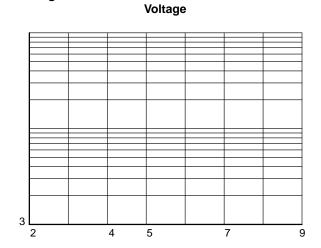


Figure 5. Transfer Characteristics



 V_{SD} , BODY DIODE FORWARD VOLTAGE (V)

Figure 6. Diode Forward Voltage vs. Current

IS, REVERSE DRAIN CURRENT (A)

NVHL040N120SC1

TYPICAL CHARACTERISTICS (continued)

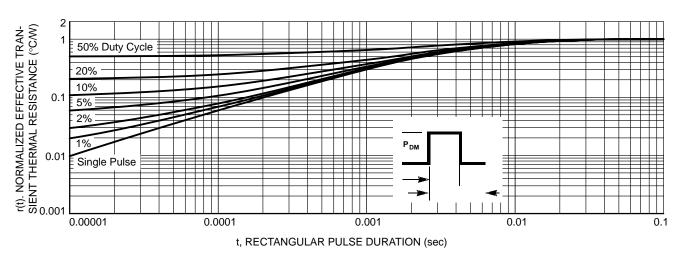


Figure 13. Junction-to-Ambient Thermal Response

